Amendments to the Claims

The following listing of claims will replace all prior versions of claims in the application.

1-10. (Canceled)

11. (Currently amended) A heat conductive foam sheet comprising a heat polymerized molded article made from a foam sheet-forming composition comprising, in combination, the following components:

a heat-polymerizable binder component comprising at least one (meth)acrylic monomer or its partial polymer,

a heat conductive filler,

a heat polymerization initiator for said binder component, and

a foaming agent;

wherein the foam sheet is a compressible, adhesive foam sheet and wherein the heat polymerization and foaming reactions of the (meth)acrylic monomer or its partial polymer occurs in the same heating step.

12. (Previously presented) A heat conductive foam sheet according to claim 11, in which said heat-polymerizable binder component further comprises a cross-linking agent, and the acrylic polymer produced as a binder upon polymerization and cross-linking of said binder component is a cross-linked product so that the resulting product has a weight-average molecular weight of less than 200,000 in the polymer chain thereof, a shearing storage modulus (G') of 1.0×10^3 to 1.0×10^5 Pa at the frequency of 1 Hz and 20°C, and optionally a loss tangent (tanδ) of 0.2 to 0.8.

13. (Previously presented) A heat conductive foam sheet according to claim 11, in which said (meth)acrylic monomer comprises a (meth)acrylic monomer having an alkyl group of no more than 20 carbons.

14. (Previously presented) A heat conductive foam sheet according to claim 11, further comprising an acrylic polymer which is composed mainly of an acrylic acid ester wherein the ester portion has 1 to 20 carbons, which has a glass transition temperature of no higher than 20°C and a weight-average molecular weight of from 500 to 100,000, and which has substantially no functional groups.

15. (Previously presented) A heat conductive foam sheet according to claim 11, in which said foaming agent comprises an inorganic foaming agent, an organic foaming agent and/or thermal expanding microcapsules.

16. (Previously presented) A heat conductive foam sheet according to claim 11, in which said foaming agent is used in an amount of 0.1 to 20 parts by weight with respect to 100 parts by weight of the (meth)acrylic monomer.

17. (Previously presented) A heat conductive foam sheet according to claim 11, in which the heat conductivity is 2 W/mK or greater.

18. (Previously presented) A heat conductive foam sheet according to claim 11, in which the void volume is 5 to 50 vol%.

19. (Currently amended) ~~Use of the heat conductive foam sheet according to claim 11, to adhere a heat radiating part to a heat generating part~~ An article comprising:

(a) a heat generating part having a first surface;

(b) a heat radiating part having a first surface; and

(c) the heat conductive foam sheet according to claim 11 disposed between the heat generating part and heat radiating part such that the foam sheet is adhered to their respective first surfaces.

20. (Currently amended) The article ~~use~~ according to claim 19, wherein the heat generating part is an electronic or electrical device.